

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	156	((printed adj circuit adj board) or "PCB") near5 ((shield or shield \$3) adj (coat\$3 or cover or coverage or cover\$3))	US-PGPUB; USPAT; USOCR	OR	ON	2009/03/26 13:24
L4	80	3 and (soldering or reflow\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2009/03/26 13:25
L7	6	("5003160"   "5128506"   "5560531"   "5560531").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/26 13:34
L8	3	7 and shield\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/26 13:35
L9	29	("4565917"   "4603730"   "4605161"   "4610886"   "4632291"   "4698774").PN. OR ("5003160").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/03/26 13:36
L10	2	9 and shield\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/26 13:40
L12	1318	(heat or thermal or temperature) adj (resistance or resistant or insulator or insulating) near5 ("PCB" or (circuit adj board) or (printed adj circuit adj board))	US-PGPUB; USPAT; USOCR	OR	ON	2009/03/26 13:47

L13	639	12 and (soldering or reflow\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2009/03/26 13:47
L14	106	13 and shield\$3	US-PGPUB; USPAT; USOCR	OR	ON	2009/03/26 13:47
L18	9	("BT" adj resin adj laminated) near20 ((printed adj circuit adj board) or "PCB")	US-PGPUB; USPAT; USOCR	OR	ON	2009/03/26 14:09
L25	15	(two or double) near5 pass near5 (solder adj reflow \$3)	US-PGPUB; USPAT; USOCR	OR	ON	2009/03/26 17:11
L27	19	reflow\$3 adj pass	US-PGPUB; USPAT; USOCR	OR	ON	2009/03/26 18:25
L35	60	((("THT" or "through-hole" or (through a dj hole) or pin) adj component) near2 (mechanical oer socket or "snap-in"))	US-PGPUB; USPAT; USOCR	OR	ON	2009/03/26 19:50
S101	848	("PCB" or (circuit adj board) or (printed adj circuit adj board)) near5 (heat\$3 adj (shield or shield\$3 or resistant or resistance))	US-PGPUB; USPAT; USOCR	OR	ON	2009/03/20 16:18
S102	172	S101 and reflow\$3	US-PGPUB; USPAT; USOCR	OR	ON	2009/03/20 16:19
S103	145	S102 and ("SMD" or "THT" or (surface adj mount \$3 adj component) or "PIH" or "pin-in-hole" or component)	US-PGPUB; USPAT; USOCR	OR	ON	2009/03/20 16:22

S110	1470	(( "PCB" or (circuit adj board) or (printed adj circuit adj board)) adj (isulat\$3 or (non adj conductive) or (heat\$3 adj (resistance or resistant)) or cover \$4))	EPO; JPO; DERWENT	OR	ON	2009/03/23 17:47
S111	193	S109 and (reflow near2 solder\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2009/03/23 17:48

**3/26/2009 9:29:24 PM****C:\Documents and Settings\maboagye\My Documents\EAST\Workspaces\10507213 method of populating and soldering a circuit board 228-214, 29-840, 174-260 FOAM 12-11-07.wsp**